

Description

Features

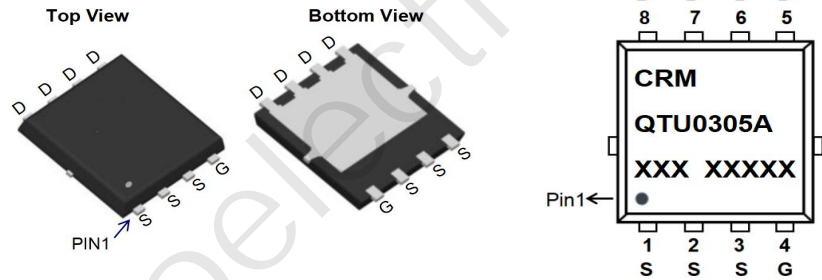
- 30V, 50A
- $R_{DS(ON)}$ Typ = 4.2mΩ @ $V_{GS} = 4.5V$
- $R_{DS(ON)}$ Typ = 5.5mΩ @ $V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQTU0305A	CRMQTU0305A	PDFN3.3x3.3-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	±12	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	50
		$T_C = 100^\circ C$	30
I_{DM}	Pulsed Drain Current ⁽¹⁾	200	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	95	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	23
$R_{\theta JC}$	Thermal Resistance, Junction to Case	5.4	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.8	1.3	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽²⁾	$V_{GS} = 4.5\text{V}, I_D = 20\text{A}$	-	4.2	5.4	mΩ
		$V_{GS} = 2.5\text{V}, I_D = 10\text{A}$	-	5.5	7.1	mΩ

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 15\text{V},$ $f = 1\text{MHz}$	-	3084	-	pF
C_{oss}	Output Capacitance		-	220	-	pF
C_{rss}	Reverse Transfer Capacitance		-	185	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 10\text{V}, I_D = 10\text{A}$	-	38	-	nC
Q_{gs}	Gate Source Charge		-	6	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	8	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 15\text{V}$ $I_D = 10\text{A}, R_{GEN} = 3\Omega$	-	12	-	ns
t_r	Turn-On Rise Time		-	36	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	42	-	ns
t_f	Turn-Off Fall Time		-	10	-	ns

Drain-Source Diode Characteristics and Max Ratings

I_S	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}, I_S = 10\text{A}$	-	-	50	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	200	A
V_{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time		-	14	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	4	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 15\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$, $I_{AS} = 19.5\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

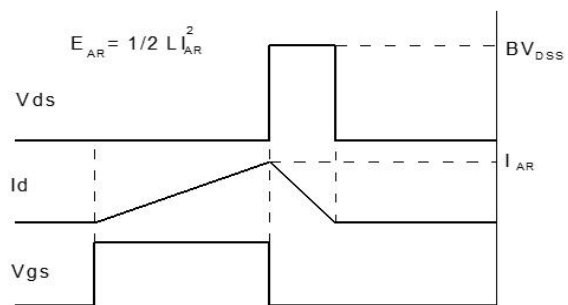
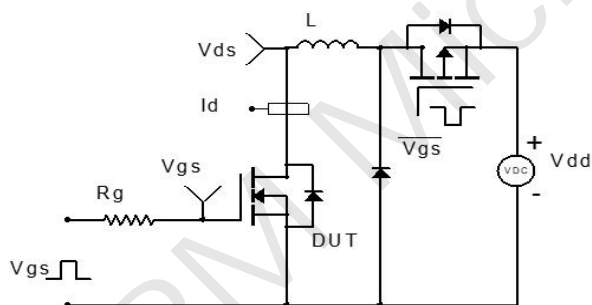
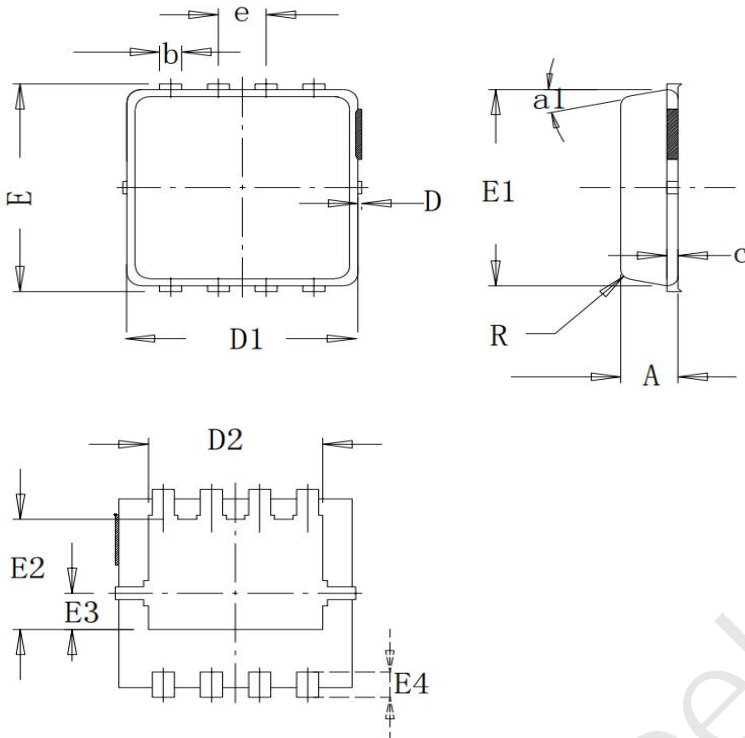


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3.3x3.3-8L)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.75	0.78	0.81
* b	0.297	0.3	0.35
c	—	0.152	—
* D	0.00	0.05	0.1
D1	3.12	3.15	3.18
* D2	—	2.35	—
* E	3.2	3.3	3.4
E1	3.09	3.12	3.15
E2	—	1.75	—
E3	—	0.575	—
* E4	—	0.4	—
R	—	0.15	—
* e	0.65BSC		
a1°	—	12°	—

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